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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
09/880,518	06/12/2001	Kun-Chih Wang	JC-7265-C	5023

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EXAMINER

NGUYEN, DILINH P

ART UNIT	PAPER NUMBER
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2814

DATE MAILED: 07/29/2002

Please find below and/or attached an Office communication concerning this application or proceeding.

Office Action Summary

Application No.

09/880,518

Applicant(s)

WANG, KUN-CHIH

Examiner

DiLinh Nguyen

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-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If the period for reply specified above is less than thirty (30) days, a reply within the statutory minimum of thirty (30) days will be considered timely.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133).
- Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☒ Responsive to communication(s) filed on 23 May 2002.
- 2a) ☒ This action is **FINAL**. 2b) ☐ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-15 is/are pending in the application.
- 4a) Of the above claim(s) _____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) _____ is/are allowed.
- 6) ☒ Claim(s) 1-15 is/are rejected.
- 7) ☐ Claim(s) _____ is/are objected to.
- 8) ☐ Claim(s) _____ are subject to restriction and/or election requirement.

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on _____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
- Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
- 11) ☐ The proposed drawing correction filed on _____ is: a) ☐ approved b) ☐ disapproved by the Examiner.
- If approved, corrected drawings are required in reply to this Office action.
- 12) ☐ The oath or declaration is objected to by the Examiner.

Priority under 35 U.S.C. §§ 119 and 120

- 13) ☐ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☐ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. _____.
3. ☐ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).
- * See the attached detailed Office action for a list of the certified copies not received.
- 14) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. § 119(e) (to a provisional application).
- a) ☐ The translation of the foreign language provisional application has been received.
- 15) ☐ Acknowledgment is made of a claim for domestic priority under 35 U.S.C. §§ 120 and/or 121.

Attachment(s)

- 1) ☐ Notice of References Cited (PTO-892)
- 2) ☐ Notice of Draftsperson's Patent Drawing Review (PTO-948)
- 3) ☐ Information Disclosure Statement(s) (PTO-1449) Paper No(s) _____
- 4) ☐ Interview Summary (PTO-413) Paper No(s) _____
- 5) ☐ Notice of Informal Patent Application (PTO-152)
- 6) ☐ Other: _____

DETAILED ACTION

1. The following is a quotation of the first paragraph of 35 U.S.C. 112:

The specification shall contain a written description of the invention, and of the manner and process of making and using it, in such full, clear, concise, and exact terms as to enable any person skilled in the art to which it pertains, or with which it is most nearly connected, to make and use the same and shall set forth the best mode contemplated by the inventor of carrying out his invention.

2. Claims 1 and 8 are rejected under 35 U.S.C. 112, first paragraph, as containing subject matter which was not described in the specification in such a way as to reasonably convey to one skilled in the relevant art that the inventor(s), at the time the application was filed, had possession of the claimed invention.

Regarding claims 1 and 8, the phrase: "...a device section and a non-device section..." are not disclosed in the specification and the drawings.

The phrase: "...a plurality of via plugs for linking up the current conduction structure and mechanical support structure..." are not disclosed in the specification and the drawings.

Claim Rejections - 35 USC § 103

3. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

4. Claims 1-7 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamaha (U.S. Pat. 6,297,563).

Yamaha discloses a semiconductor device (cover Fig., column 5, lines 60 et seq.) comprising:

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a substrate 10;

a bonding pad layer 32 (column 10, line 65) above the substrate;

an area structure A between the bonding pad layer and the substrate for connecting the bonding pad layer and the substrate electrically, wherein the area A structure includes:

a plurality of conductive metallic layers 14a, 20a and 26a, wherein each conductive metallic layer is at a different height level from the substrate, and

a plurality of conductive plugs 18a, 24a and 30a for linking neighboring conductive metallic layers and the conductive metallic layers with the bonding pad layer and the substrate;

an area structure B between the bonding pad layer and the substrate, wherein the area B structure includes:

a plurality of conductive metallic layers 14b, 20b and 26b, wherein each conductive metallic layer is at a different height level from the substrate, and

a plurality of conductive plugs 18b and 24b for linking neighboring conductive metallic layers and the conductive metallic layers with the bonding pad layer and the substrate;

wherein the plugs 24b for linking up the area structure A and the area structure B with the bonding pad layer 32.

an insulation layers 12, 16, 22 and 28 between the bonding pad layer, the area A and B structures.

Yamaha discloses the claimed invention but does not specifically point out a current conduction structure and a mechanical support structure. However, the structure A of Yamaha is inherently the current conduction structure and the area B is a mechanical support structure for the device.

- Regarding claims 2-4 and 6-7, Yamaha discloses: each conductive metallic layer in the structure A has a smaller cross-sectional area than each metallic layer in the structure B;
a number of metallic layers in the structures A and B are identical and at an identical height level; and
the conductive plugs between neighboring conductive metallic layers, between the bonding pad and metallic layer and between the metallic layer and the substrate of the structures A and B are evenly distributed.
- Regarding claim 5, Yamaha discloses the claimed invention except for the number of metallic layers in the structure A differs from number metallic layers in the structure B. It would have been obvious matter of design choice within the ordinary skill of one in the art.

3. Claims 8-15 are rejected under 35 U.S.C. 103(a) as being unpatentable over Yamaha (U.S. Pat. 6,297,563) in view of Lu et al. (U.S. Pat. 6,100,573).

Yamaha discloses the claimed invention except for the metallic layers in both structures A and B are directly contact with the substrate. Lu et al. disclose the first metallic layers 304 are directly contact with the substrate 300 (cover Fig., column 3, lines 25 et seq.) to connect the substrate to the bonding pad. Therefore, it would have

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been obvious to one having a ordinary skill in the art at the time the invention was made to provide the structure with the substrate connected to the bonding pad as shown by Lu et al.

Response to Arguments

Applicant's arguments filed 5/23/02 have been fully considered but they are not persuasive.

The applicant argues that Yamaha fails to disclose a plurality of via plugs for linking up the current conduction structure and the support structure with the bonding pad layer.

The Examiner disagrees.

The phrase: "...a plurality of via plugs..." is a new subject matter. The drawings and specification disclose the plugs under the mechanical support structure and current conduction structure for linking up the current structure and the support structure with the bonding pad. There are no other plugs out side the mechanical structure and current structure.

Yamaha disclose the claimed invention and the structures A and B of Yamaha are inherent by the current conduction structures and mechanical structure for the device. The current conduction structure is the mechanical support structure for the device. Moreover, the plugs 24b for linking up the area structure A and the area structure B with the bonding pad layer 32.

Conclusion

Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire **THREE MONTHS** from the mailing date of this action. In the event a first reply is filed within **TWO MONTHS** of the mailing date of this final action and the advisory action is not mailed until after the end of the **THREE-MONTH** shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than **SIX MONTHS** from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to DiLinh Nguyen whose telephone number is (703) 305-6983. The examiner can normally be reached on 8:00AM - 6:00PM (M-F).

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, OLIVIA CHAUDHURI can be reached on (703) 306-2794. The fax phone numbers for the organization where this application or proceeding is assigned are (703) 308-7722 for regular communications and (703) 308-7724 for After Final communications.

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Any inquiry of a general nature or relating to the status of this application or proceeding should be directed to the receptionist whose telephone number is (703) 308-0956.

DLN

July 18, 2002



OLIK CHAUDHURI
SUPERVISORY PATENT EXAMINER
TECHNOLOGY CENTER 2800